

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicants : Roy Knechtel and Andrej Lenz
Serial No. : 10/580,361
Filing Date : 04/18/2007
Title : PRODUCTION OF SEMICONDUCTOR SUBSTRATES
WITH BURIED LAYERS BY JOINING (BONDING)
SEMICONDUCTOR WAFERS
Docket : LEO 003 PA
Art Unit : 2811
Examiner :
Confirmation No. : 1718

MS Amendment
Commissioner for Patents
PO Box 1450
Alexandria VA 22313-1450

Sir:

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §§ 1.56, 1.97, AND 1.98

Supplemental to the Information Disclosure Statement submitted May 23, 2006, Applicants submit herewith patents, publications, and other information of which they are aware, which they believe may be material, as defined in 37 CFR § 1.56(b), to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56(a). While the information referred to in this Supplemental Information Disclosure Statement may be material pursuant to 37 CFR § 1.56(b), the filing of this Supplemental Information Disclosure Statement is not intended to, pursuant to 37 CFR § 1.97(h), constitute an admission that any patent, publication, or other information referred to is, or is considered to be, material to the patentability of this invention. Further, pursuant to 37 CFR § 1.97(g), the filing of this Statement should not be construed as a statement that a search has been made or that no other material information exists.

Docket No. LEO 003 PA
Application No. 10/580,361
Page 2

A listing of the item of information cited is attached on PTO Form PTO/SB/08, substitute form for 1449 /PTO. A copy of the item is enclosed for the convenience of the Examiner.

This Supplemental Information Disclosure Statement is being filed within the period set forth in 37 CFR § 1.97(b) because it is believed to be filed before the mailing of a first Office action on the merits.

Respectfully submitted,

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/Richard C. Stevens/

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June 2, 2008